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1 RBIC1 Dynamic-Link Library (DLL)

The calibration DLL described in this document is designed to expedite the calibration process for the ZSC31050, ZSC31150, ZSSC313x, ZSSC3154, and ZSSC3170 Sensor Signal Conditioner (SSC) products. Unless otherwise noted, the term SSC IC will be used in this document to refer to these five products.

The calibration process compensates the sensor input offset, sensor linearization, and sensor’s sensitivity temperature dependency. It uses a polynomial function called ZMD31050_cal1, which calculates coefficients for up to 3rd order linearization compensation and up to 2nd order for the temperature compensation. The RBIC1 DLL is contained in the Evaluation Software installation folder.

Coefficients resulting from ZMD31050_cal1 are stored in the SSC EEPROM memory. Table 1.1 provides a list of the resulting coefficients.

<table>
<thead>
<tr>
<th>Coefficient Name</th>
<th>EEPROM Address</th>
<th>Polynomial Function</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>C0</td>
<td>00_{HEX}</td>
<td>Offset</td>
<td>Input signal when no sensor excitation is present</td>
</tr>
<tr>
<td>C1</td>
<td>01_{HEX}</td>
<td>Gain</td>
<td>Sensor signal gain value</td>
</tr>
<tr>
<td>C2</td>
<td>02_{HEX}</td>
<td>Linearization</td>
<td>2nd order non-linearity for three-point calibration</td>
</tr>
<tr>
<td>C3</td>
<td>03_{HEX}</td>
<td>Linearization</td>
<td>3rd order non-linearity for four-points calibration</td>
</tr>
<tr>
<td>C4</td>
<td>04_{HEX}</td>
<td>Temperature compensation</td>
<td>1st order temperature coefficient sensor offset</td>
</tr>
<tr>
<td>C5</td>
<td>05_{HEX}</td>
<td>Temperature compensation</td>
<td>2nd order temperature coefficient sensor offset</td>
</tr>
<tr>
<td>C6</td>
<td>06_{HEX}</td>
<td>Temperature compensation</td>
<td>1st order temperature coefficient gain dependency</td>
</tr>
<tr>
<td>C7</td>
<td>07_{HEX}</td>
<td>Temperature compensation</td>
<td>2nd order temperature coefficient gain dependency</td>
</tr>
</tbody>
</table>
Figure 1.1 illustrates a typical signal flow from measuring the physical value to the output of the conditioned result with offset compensation and gain compensation to meet the voltage output targets and signal linearization requirements for the application.

**Figure 1.1  SSC Block Diagram and Signal Flow for a Pressure Sensor Example**

2  Calibration Sequence

A typical calibration flow contains five steps in the following order:

1. Set-up and initialization
2. Data collection
3. Coefficient calculation
4. EEPROM programming
5. Verification

These five steps are very similar for all applicable products; there might be some insignificant differences in the Evaluation Software user interface.

Connect the SSC IC to the user’s PC using the selected interface applicable to the product: I²C™*, OWI, LIN, or SPI. Refer to the product’s *Functional Description* document for the available command set.

* I²C™ is a trademark of NXP.
2.1. Set-up and Initialization

Prior to data collection, the SSC must be configured so that the analog front-end (AFE), temperature measurement, and additional SSC functions fit the sensor's parameters and application requirements. This includes gain selection, sensor signal range, ADC resolution, temperature sensor in use, output format, and diagnostic functions.

The goal is to adjust the gain so the sensor signal is as close as possible to the acceptable ADC voltage range for the full operational temperature range. For this, the sensor span, offset, and tolerances must be taken into account.

Next, write the initial configuration into the RAM or the EEPROM of the SSC IC.

Note: Setting initial coefficients values is not required (initially coefficients can be set to 0 or any value).

Figure 2.1 Basic Analog Front-End
2.2. Data Collection

After the coefficients in EEPROM are initialized, data collection can begin. The minimum number of calibration points required varies between two and as many as eight for the main sensor and two or three for the temperature sensor. This depends on the precision required and the behavior of the sensor in use. In general, taking more calibration points will result in a better calibration.

Figure 2.2 shows the expected placement of calibration points for the different calibration options. The order of the points taken is not important; however, the number of points per temperature must be followed or the calibration might fail. The location and order of the temperature values is also not important – however for best results, the temperatures should be spread evenly throughout the user's specification range. It is important to keep the calibration points as orthogonal as possible to maximize calibration accuracy.

Figure 2.2 Calibration Points

The calibration point configuration can be any setup from 2-points linear calibration to 3rd order non-linearity compensation and 2nd order temperature dependency compensation.
2.3. Coefficient Calculation

2.3.1. Function Call for Main Sensor Channel

\texttt{ZMD31050\_cal1} (Zp1m, Zp2m, Zp4m, Zp3m, Zp1u, Zp2u, Zp1l, Zp2l, A, B, M2, M, Ztmed, Ztupp, Ztlow, adc\_res, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);

\textit{Figure 2.3 Calibration Points and Target Values for Sensor Measurements}

\begin{tabular}{|l|l|l|l|l|}
\hline
\textbf{Name} & \textbf{Description} & \textbf{Type} & \textbf{Range} & \textbf{Condition} \\
\hline
ZMD31050\_cal1 & Function call, main sensor channel & int & 4 bytes & Returns 0 if successful \\
Zp1m & Sensor minimum output & float & ±2\textsuperscript{15} & Required \\
Zp2m & Sensor maximum output & float & ±2\textsuperscript{15} & Required \\
Zp3m & Sensor output (2nd order nonlinearity) & float & ±2\textsuperscript{15} & 0 \\
Zp4m & Sensor output (3rd order nonlinearity) & float & ±2\textsuperscript{15} & 0 \\
Zp1u & Sensor minimum output & float & ±2\textsuperscript{15} & 0 \\
Zp2u & Sensor maximum output & float & ±2\textsuperscript{15} & 0 \\
Zp1l & Sensor minimum output & float & ±2\textsuperscript{15} & 0 \\
Zp2l & Sensor maximum output & float & ±2\textsuperscript{15} & 0 \\
A & Target output value in [\%] multiplied by 0.01 for digital output target & float & 0 to 1 & Required \\
M & & float & 0 to 1 & 0 \\
M2 & & float & 0 to 1 & 0 \\
B & & float & 0 to 1 & Required \\
\hline
\end{tabular}

Table 2.1 List of Calibration Parameters
<table>
<thead>
<tr>
<th>Name</th>
<th>Description</th>
<th>Type</th>
<th>Range</th>
<th>If not used</th>
<th>Condition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ztmed</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>-33000.0</td>
<td>Medium temperature</td>
</tr>
<tr>
<td>Ztupp</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>-33000.0</td>
<td>Upper temperature</td>
</tr>
<tr>
<td>Ztlow</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>-33000.0</td>
<td>Lower temperature</td>
</tr>
<tr>
<td>adc_res</td>
<td>ADC resolution</td>
<td>int</td>
<td>9 to 16</td>
<td>-</td>
<td>Given in bits</td>
</tr>
<tr>
<td>C0 to C7</td>
<td>Calculated coefficients</td>
<td>float</td>
<td>4 bytes</td>
<td>0</td>
<td>Results upon success</td>
</tr>
</tbody>
</table>

Data acquisition commands: \textbf{D8}_{\text{HEX}} for sensor and \textbf{D9}_{\text{HEX}} for calibration temperature.

Command format: [7bit Slave Address] [0] [8-bit command]

Evaluation software command:

- \textit{i^2C™} interface: \texttt{IW_78001D8}
- OWI interface: \texttt{OW_78001D8}
- LIN interface: \texttt{LW_3c0087F05B4FFFFFFFFFFF}

\subsection{Function Call for Temperature Channel}

\texttt{TQuad} (Ztlow, Ztupp, Ztmed, Tlow, Tupp, Tmed, adc_res, \&Ct0, \&Ct1, \&Ct2);

\texttt{TLin} (Ztmed, Ztupp, Tmed, Tupp, \&Ct0, \&Ct1);

\textbf{Table 2.2} List of Temperature Calculation Function Parameters

<table>
<thead>
<tr>
<th>Name</th>
<th>Description</th>
<th>Type</th>
<th>Range</th>
<th>Condition</th>
</tr>
</thead>
<tbody>
<tr>
<td>TQuad</td>
<td>Function call, temperature channel 2\textsuperscript{nd} order</td>
<td>bool</td>
<td></td>
<td>Returns 0 if successful</td>
</tr>
<tr>
<td>TLin</td>
<td>Function call, temperature channel linear</td>
<td>bool</td>
<td></td>
<td>Returns 0 if successful</td>
</tr>
<tr>
<td>Ztmed</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>Medium temperature</td>
</tr>
<tr>
<td>Ztupp</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>Upper temperature</td>
</tr>
<tr>
<td>Ztlow*</td>
<td>Temperature sensor</td>
<td>float</td>
<td>±2\textsuperscript{15}</td>
<td>Lower temperature</td>
</tr>
</tbody>
</table>
| Tlow    | \begin{align*}
temp_{\text{range}} &= \frac{\text{Target}_{\text{max}} - \text{Target}_m\text{in}[-\%VDDA]}{100} + \frac{\text{Target}_m\text{in}[-\%VDDA]}{100} \\
&\text{Where VDDA stands for analog power supply and ADC reference voltage of the IC.}
\end{align*} & float | 0 to 1   | \(temp_{\text{range}} = T_{\text{low}} - T_{\text{min}}\) |
| Tmed    | \begin{align*}
temp_{\text{range}} &= \frac{\text{Target}_{\text{max}} - \text{Target}_m\text{in}[\text{[\%VDDA]}]}{100} + \frac{\text{Target}_m\text{in}[\text{[\%VDDA]}]}{100} \\
&\text{Where VDDA stands for analog power supply and ADC reference voltage of the IC.}
\end{align*} & float | 0 to 1   | \(temp_{\text{range}} = T_{\text{med}} - T_{\text{min}}\) |
| Tupp    | \begin{align*}
&\text{Where VDDA stands for analog power supply and ADC reference voltage of the IC.}
\end{align*} & float | 0 to 1   | \(temp_{\text{range}} = T_{\text{upp}} - T_{\text{min}}\) |
| adc_res | ADC resolution, temperature channel                              | int    | 9 to 16   | Given in bits           |
| Ct1 to Ct3 | Calculated coefficients, temperature channel                    | float  | 4 bytes   | Result upon success     |
Data acquisition commands: \texttt{DA\textsubscript{HEX}}

Command format: [7bit Slave Address] [0] [8-bit command]

Evaluation Software Command:

\begin{itemize}
  \item I\textsuperscript{2}C™ interface: IW\_78001DA
  \item OWI interface: OW\_78001DA
  \item LIN interface: LW\_3c0087F05B4DAFFFFFFFFFF
\end{itemize}

\textbf{Figure 2.4} Calibration Points and Target Values for Temperature Measurement

![ Calibration Points and Target Values for Temperature Measurement ]

The upper and lower limits (Max. and Min.) are usually selected as 10\% and 90\% of the ADC reference voltage (the analog voltage supply). Note that this varies depending on the SSC IC. In this input range, the ADC has the best performance for linearity.
2.3.3. Returned Error Codes

Note: bit [0] is not used

Table 2.3 Returned Error Codes

<table>
<thead>
<tr>
<th>Flags</th>
<th>HEX</th>
<th>Bit</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>0000 0000 0000 0010</td>
<td>0002&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1]</td>
<td>No solution found for given input data.</td>
</tr>
<tr>
<td>0000 0001 0000 0010</td>
<td>0102&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1] and bit[8]</td>
<td>Calculated coefficients are out of range (linear calibration).</td>
</tr>
<tr>
<td>0000 0010 0000 0010</td>
<td>0202&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1] and bit[9]</td>
<td>Offset: No solution found or coefficients are out of range.</td>
</tr>
<tr>
<td>0000 0100 0000 0010</td>
<td>0402&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1] and bit[10]</td>
<td>Gain: No solution found or coefficients are out of range.</td>
</tr>
<tr>
<td>0000 1000 0000 0010</td>
<td>0802&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1] and bit[11]</td>
<td>2&lt;sup&gt;nd&lt;/sup&gt; order: No solution found or coefficients are out of range.</td>
</tr>
<tr>
<td>0001 0000 0000 0010</td>
<td>1002&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[1] and bit[12]</td>
<td>3&lt;sup&gt;rd&lt;/sup&gt; order: No solution found or coefficients are out of range.</td>
</tr>
<tr>
<td>0000 0000 0000 0100</td>
<td>0004&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[2]</td>
<td>Range check error.</td>
</tr>
<tr>
<td>0000 0000 0000 1000</td>
<td>0008&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[3]</td>
<td>Temperature behavior linearization calculation error.</td>
</tr>
<tr>
<td>0000 0001 0000 1000</td>
<td>0108&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[3] and bit[8]</td>
<td>Offset temperature coefficient calculation (C4 and C5).</td>
</tr>
<tr>
<td>0000 0000 0001 0000</td>
<td>0010&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[4]</td>
<td>Coefficients range check error.</td>
</tr>
<tr>
<td>0000 0001 0001 0000</td>
<td>0110&lt;sub&gt;HEX&lt;/sub&gt;</td>
<td>bit[4] and bit[8]</td>
<td>Coefficient range check (C0 and C1) error.</td>
</tr>
</tbody>
</table>
2.3.4. Calculation Examples

| ADC max.: | 90%[VDDA] |
| ADC min.: | 10%[VDDA] |
| ADC resolution: | 14 bit |
| Data points: | 10%, 50%, 70% and 90% |
| Temperature points: | -40°C, -5°C, 25°C, 85°C and 125°C |

Linear (two points, no non-linearity and temperature compensation)
\[
\text{ZMD31050\_cal1 (data #1, data #2, 0, 0, 0, 0, 0.1, 0.9, 0, 0, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);}
\]

2\(^{nd}\) order non-linearity compensation (three points at 10%, 50%, and 90%, no temperature compensation)
\[
\text{ZMD31050\_cal1 (data #1, data #2, 0, data #3, 0, 0, 0, 0.1, 0.9, 0, 0.5, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);}
\]

3\(^{rd}\) order non-linearity compensation (four points at 10%, 50%, 70%, and 90%, no temperature compensation)
\[
\text{ZMD31050\_cal1 (data #1, data #2, data #4, data #3, 0, 0, 0, 0, 0.1, 0.9, 0.7, 0.5, -33000, -33000, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);}
\]

3\(^{rd}\) order non-linearity and 2\(^{nd}\) order temperature compensation (8 points for sensor and 3 points for temperature)
\[
\text{ZMD31050\_cal1 (data #1, data #2, data #4, data #3, data #5, data #6, data #7, data #8, 0.1, 0.9, 0.7, 0.5, temp#1, temp#2, temp#3, 14, &C0, &C1, &C2, &C3, &C4, &C6, &C5, &C7);}
\]
\[
\text{TQuad (temp#1, temp#2, temp#3, 0.27, 0.71, 0.42, 14, &Ct0, &Ct1, &Ct2);}
\]

2.4. EEPROM Programming

Programming of the SSC IC can be done via the Evaluation Software provided for each SSC IC. Software can be downloaded from the product pages on [www.IDT.com](http://www.IDT.com).

Refer to the [Evaluation Kit Description](http://www.IDT.com) for the SSC IC for further details.
2.5. Verification

*Figure 2.5 Calculation and Measurement Results*

After successful calibration, the output of the SSC IC should vary between the target limits specified during calibration. For digital data, the readout values match the resolution of the data format used.

For analog output, the output voltage is generated using a resistor-string digital-to-analog converter (DAC) with 5632 steps, of which 5120 steps (256 to 5375) can be addressed. As a result, an adjustable range from 5% to 95% of the supply voltage is guaranteed, including all possible tolerances.

Visit IDT’s website [www.IDT.com](http://www.IDT.com) or contact your nearest sales office for the latest version of various support documents.
3 Glossary

<table>
<thead>
<tr>
<th>Term</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADC</td>
<td>Analog-to-Digital Converter</td>
</tr>
<tr>
<td>DAC</td>
<td>Digital to Analog Converter</td>
</tr>
<tr>
<td>DLL</td>
<td>Dynamic-Link Library</td>
</tr>
<tr>
<td>SSC</td>
<td>Sensor Signal Conditioner</td>
</tr>
</tbody>
</table>

4 Document Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1.00</td>
<td>July 9, 2015</td>
<td>First release.</td>
</tr>
<tr>
<td></td>
<td>April 26, 2016</td>
<td>Changed to IDT branding.</td>
</tr>
</tbody>
</table>
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Corporate Headquarters
TOYOSU FORESIA, 3-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

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